



High yield, high throughput ultrasonic flip-chip bonding.

MD-P300 Flip-chip Bonder

The MD-P300 Flip-chip Bonder is process-flexible, combining flip-chip and thermosonic bonding in a single, small-footprint solution. The MD-P300 contributes to the cost-effective production (high yield, high throughput) of value-added devices. The MD-P300 can achieve high speed and high accuracy bonding through its low gravity point and lightweight bonding head. The MD-P300 supports 300 mm (12") wafers, and is an ideal solution for COB hybrid assembly in combination with an in-line Panasonic SMT placement machine. The MD-P300 is capable of fast cycle times and a placement accuracy of $\pm 5 \mu\text{m}$ at 0.5 seconds per IC (dry run) - with thermosonic processes at 0.65 seconds, including process times.

Key Features

Easy process exchange

Real-time inspection

User-friendly operation

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<https://ap.connect.panasonic.com/sg/en/md-p300-flip-chip-bonder>

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| Model Number | NM-EFF1C |
| Productivity | C4: 0.65s/IC (including dipping motion) |
| | Thermosonic: 0.65s/IC (including US process time of 0.2s) |
| Placement Accuracy | XY (3 σ at PFSC conditions): $\pm 5\mu\text{m}$ |
| Substrate dimensions | L 50 × W 50 to L 330 × W 330 (Heating specifications: L 330 × W 220mm) |
| Die dimensions (mm) | L 1 × W 1 to L 25 × W 25 (Thermosonic: L7 × W7) |
| Number of die types | Up to 12 product types (AWC specifications) nozzle type |
| Die Supply | Wafer frame 12 inches (Option: 8 inches) |
| Bonding Load | VCM head: 1N to 50N (Option: 2N to 100N) |
| Head Heating | Thermosonic: Up to 300°C |
| Substrate Heating | Constant heating, Up to 200°C (Heating bonding stage specifications: Max. substrate size L 330 × W 220mm) |
| Power Source | 3-phase AC 200V \pm 10V, 50/60Hz, |
| | Up to 4kVA (Up to 7kVA for heating specification) |
| Pneumatic Source | 0.4MPa, 50L/min (A.N.R.) (Up to 150L/min for full-featured machine including cooling air) |
| Dimensions (mm) | W 1380 × D 1640 × H 1430 (without loader / unloader) |
| Mass (Weight) | 2300kg (without loader / unloader) |